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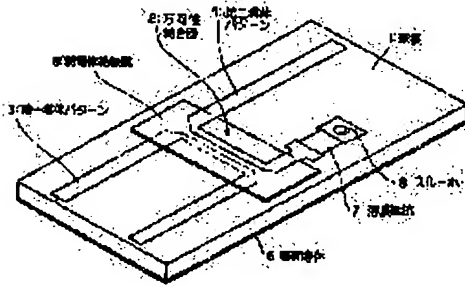
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(54) COUPLING ELEMENT PROVIDED WITH DIELECTRIC INSULATION FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To form the insulation film of a dielectric between the conductor patterns of a substrate surface, to improve a coupling degree between the conductor patterns by a simple structure while securing the degree of freedom on element design and to adjust the coupling degree of the conductor patterns even after the formation of an element.

SOLUTION: The dielectric insulation film 5 is formed between first and second conductor patterns 3 and 4 for constituting a directional coupler 2 on the substrate 1 and a part of the dielectric insulation film 5 is positioned at the upper part of the part for constituting the coupler of the first conductor pattern 3. Also, a part of the dielectric insulation film 5 is positioned at the lower part of the part for constituting the coupler of the second conductor pattern 4 and the two conductor patterns 3 and 4 are vertically piled up through the dielectric insulation film 5.



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